MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

48 LEAD LQFP, 7x7, 0.5P
CASE 932AA-01
ISSUE A

DATE 13 OCT 2008

NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
3. DATUM PLANE H IS LOCATED AT BOTTOM OF LEAD AND IS CONSIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS T, U, AND Z TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS D AND E TO BE DETERMINED AT SEATING PLANE Y.
6. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 PER SIDE. DIMENSIONS D1 AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
7. DIMENSION b DO NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE b DIMENSION TO EXCEED 0.350.
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SCALE 2:1

DETAIL F
DETAIl K

SECTION G-G

NOTE 9

EXACT SHAPE OF EACH CORNER IS OPTIONAL.

G

A1

PLATING

BASE METAL

L1

H

L

L1

R

S

T

U

Z

SECTION G-G

0.08 Y T-U Z

DETAIL F

0.250 GAUGE PLANE

GAUGE PLANE

SEATING PLANE

TOP & BOTTOM

(1) 0.15

R

S

0.2 REF

1.0 REF

0.15

0.25

1

5

XXXXX

XXXXX

AWLYYWWG

XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

DOCUMENT NUMBER: 98AON13058D
DESCRIPTION: 48 LEAD LQFP 7X7X1.4, 0.5 PITCH

Electronic versions are uncontrolled except when accessed directly from the Document Repository.
Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

© Semiconductor Components Industries, LLC, 2019 www.onsemi.com